

a semiconductor element and at least one security coating provided on a first side of the substrate so as to block visual access to secure data, the at least one security coating including at least two powdery fillers incorporated in a matrix,

wherein a first powdery filler scatters at least visible light, and a difference between a refractive index of the first powdery filler and that of the matrix is at least 0.3, and the coating comprises a second powdery filler which is a substantial absorber of radiation of wavelengths in the range of about 800 to 1400 nm and is free of heavy metals.

2. (Twice Amended) A semiconductor device as claimed in Claim 1, wherein the second filler comprises TiN.

3. (Twice Amended) A semiconductor device as claimed in Claim 1, wherein the first filler comprises TiO_2 .

4. (Twice Amended) A semiconductor device as claimed in Claim 1, wherein the matrix of the security coating comprises monoaluminumpophosphate.

5. (Twice Amended) A semiconductor device as claimed in Claim 1, where the security coating has a thickness of less than 3 um.

6. (Twice Amended) A semiconductor device as claimed in Claim 1, further comprising a light-sensitive element and an element containing data, wherein the light-sensitive element and the element containing data are covered by the security coating and wherein the light-sensitive element, after the coating is damaged, reacts to exposure to visible light by inducing a permanent change of state of the element containing data.

7. (Twice Amended) A semiconductor device as claimed in Claim 1, further comprising a light-sensitive element and an electrically programmable element containing data, wherein the light-sensitive element and the element containing data are covered by the security coating and the light sensitive element, after the coating is damaged, reacts to exposure to visible light by inducing erasure of the data and by bringing the electrically programmable element into a non-programmable state.

8. (Twice Amended) A smartcard provided with a semiconductor device comprising a memory and a security coating which comprises a